

KPBA-2006SURKZGKC

2.0 mm x 0.6 mm Right Angle SMD Chip LED Lamp



DESCRIPTIONS

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- · It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

FEATURES

- Side Looking Dual Color Chip LED, 0.6 mm thickness
- Low power consumption
- Wide viewing angle
- · Ideal for backlight and indicator
- EIA STD package
- · Tinned pads for improved solderability
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- Halogen-free
- RoHS compliant

APPLICATIONS

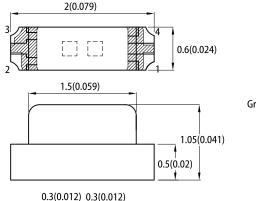
- Backlight
- · Status indicator
- Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

ATTENTION

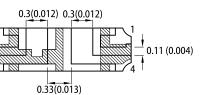
Observe precautions for handling electrostatic discharge sensitive devices

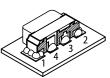


PACKAGE DIMENSIONS

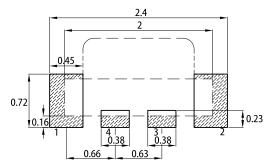








RECOMMENDED SOLDERING PATTERN



Notes

All dimensions are in millimeters (inches).
Package dimensions tolerance is ±0.1(0.004") unless otherwise noted.
The specifications, characteristics and technical data described in the datasheet are subject to

change without prior notice. 4. The device has a single mounting surface. The device must be mounted according to the specifications. 5. For right angle SMD LEDs, the solder stencil should be at least 5mil in thickness, to prevent poor solder wetting due to insufficient solder paste.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	lv (mcd) @ 20mA ^[2]		Viewing Angle ^[1]	
			Min.	Тур.	201/2	
KPBA-2006SURKZGKC	Hyper Red (AlGaInP)	- Water Clear	60	240		
			*20	*80	4409	
	Green (InGaN)		100	450	140°	
			*100	*450		

Notes

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous flux: +/-15%.
* Luminous intensity value is traceable to CIE127-2007 standards.

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
Parameter			Тур.	Max.	Unit
Wavelength at Peak Emission I_F = 20mA	λ_{peak}	Hyper Red Green	645 515	-	nm
Dominant Wavelength I _F = 20mA	λ_{dom} ^[1]	Hyper Red Green	630 525	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	Hyper Red Green	28 35	-	nm
Forward Voltage I _F = 20mA	V _F ^[2]	Hyper Red Green	1.95 3.3	2.5 4.1	V
Reverse Current (V _R = 5V)	I _R	Hyper Red Green	-	10 50	μA
Temperature Coefficient of λ_{peak} I_F = 20mA, -10°C \leq T \leq 85°C	TC_{\lambdapeak}	Hyper Red Green	0.14 0.05	-	nm/°C
Temperature Coefficient of λ_{dom} I_F = 20mA, -10°C \leq T \leq 85°C	TC _{λdom}	Hyper Red Green	0.05 0.03	-	nm/°C
Temperature Coefficient of V_F I_F = 20mA, -10°C \leq T \leq 85°C	TCv	Hyper Red Green	-1.9 -3.0	-	mV/°C

Notes:

1. The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd : ±1nm.)
2. Forward voltage: ±0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Devementer	Symbol	Va		
Parameter		Hyper Red	Green	Unit
Power Dissipation	P _D	75	82	mW
Reverse Voltage	V _R	5	5	V
Junction Temperature	TJ	115	115	°C
Operating Temperature	T _{op}	-40 To +85		°C
Storage Temperature	T _{stg}	-40 To +85		°C
DC Forward Current	I _F	30	20	mA
Peak Forward Current	I _{FP} ^[1]	185	100	mA
Electrostatic Discharge Threshold (HBM)	-	3000	450	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	730	760	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[2]	620	660	°C/W

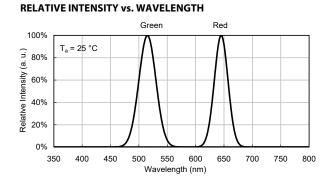
ABSOLUTE MAXIMUM RATINGS at $T_A=25^{\circ}C$

Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. R_{th JA}, R_{th JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad). 3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

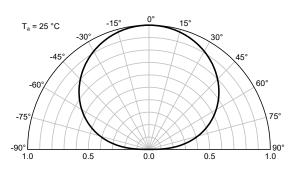
Kingbright

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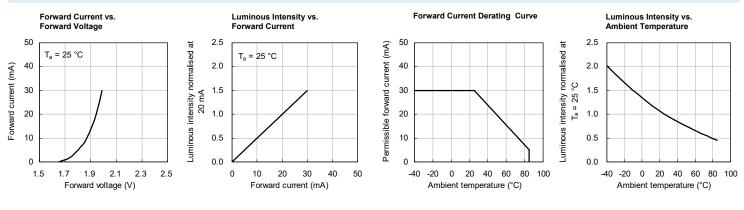
TECHNICAL DATA

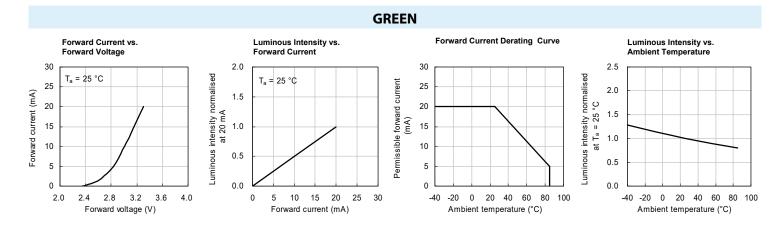


SPATIAL DISTRIBUTION



HYPER RED

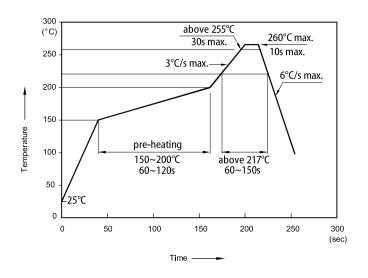




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REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

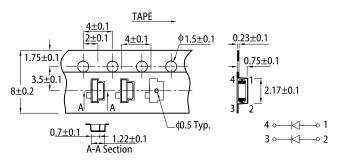


Notes

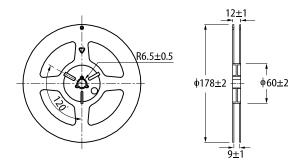
Notes: 1. Don't cause stress to the LEDs while it is exposed to high temperature. 2. The maximum number of reflow soldering passes is 2 times. 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might

cause damage to the product.

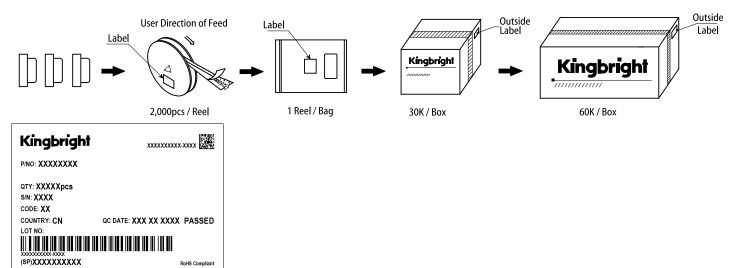
TAPE SPECIFICATIONS (units : mm)



REEL DIMENSION (units : mm)



PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer 2 to the latest datasheet for the updated specifications. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If
- 3.
- customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance. 4
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- 6